

# **Errata for FXAS21002C**

This errata sheet describes the functional problems known at the release date of this document.

#### **Revision History**

Rev	Date	Description
0	2/3/2015	Added E1: SPI Multipoint Communication
0.1	5/1/2015	E1 Fix Plan, Changed the date from WW19'2015 to WW32'2015 (2 places)

#### Contents

1
2
2
•

## **1** Part Identification

The following errata affect the behavior of all production FXAS21002C devices.





## 2 Errata

## 2.1 E1: SPI Multipoint Communication

## Problem

FXAS21002C does not support *multi-point* 4-wire SPI communication protocol (multiple slave devices on the bus).

FXAS21002C, when connected for a 4-wire SPI communication with the master, does not tri-state the MISO line when the SPI\_CS\_B (SPI chip select, Active low) pin is deasserted (logic high). This leads to a bus conflict if there are multiple devices on the same SPI bus. As the part pulls MISO down to GND, instead of tri-stating, this part blocks the other slave devices on the bus from sending data to the master by means of 4-wire SPI communication.

## Workarounds

Three possible workarounds are associated with the erratum.

### Workaround 1

Add a tri-state buffer with the MISO line and the SPI\_CS\_B line as inputs to the buffer (see Figure 1).



Figure 1. Typical application circuit with addition of tri-state buffer

### Workaround 2

Use I<sup>2</sup>C communication instead of SPI 4-wire communication as the part's I<sup>2</sup>C communication works as expected with multiple slave devices on the bus.



### Workaround 3

Use 3-wire SPI communication with FXAS21002C and all other slave devices on the SPI bus.

If the device is connected and configured to operate in 3-wire SPI mode, it works as expected with multiple slave devices on the bus with the only condition that all slave devices on the bus must be connected for a 3-wire SPI communication with the master. In this configuration, FXAS21002C's SA0/MISO pin must be left unconnected.

## **Fix Plan**

#### A fix for E1: SPI Multipoint Communication is planned.

An ASIC revision is planned for the first half of 2015. Parts not subject to this errata will be identifiable by means of a clean date code currently targeted for WW32'2015. All material manufactured WW32'2015 and later will not be subject to this errata.



How to Reach Us:

Home Page: freescale.com

Web Support: freescale.com/support Information in this document is provided solely to enable system and software implementers to use Freescale products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits based on the information in this document. Freescale reserves the right to make changes without further notice to any products herein.

Freescale makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale data sheets and/or specifications can and do vary in different applications, and actual performance may vary over time. All operating parameters, including "typicals," must be validated for each customer application by customer's technical experts. Freescale does not convey any license under its patent rights nor the rights of others. Freescale sells products pursuant to standard terms and conditions of sale, which can be found at the following address: freescale.com/SalesTermsandConditions.

Freescale and the Freescale logo are trademarks of Freescale Semiconductor, Inc., Reg. U.S. Pat. & Tm. Off. All other product or service names are the property of their respective owners.

© 2015 Freescale Semiconductor, Inc.

Document Number: FXAS21002CER Revision 0.1, 5/2015

